PROCEEDINGS OF SPIE

Laser Applications in Microelectronic and Optoelectronic Manufacturing (LAMOM) XXVI

Carlos Molpeceres
Jie Qiao
Aiko Narazaki
Editors

6–11 March 2021
Online Only, United States

Sponsored by
Okamoto Optics Works (Japan)
Plymouth Grating Laboratory (United States)

Published by
SPIE

Volume 11673

Proceedings of SPIE 0277-786X, V. 11673

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Please use the following format to cite material from these proceedings:
Author(s), "Title of Paper," in *Laser Applications in Microelectronic and Optoelectronic Manufacturing (LAMOM) XXVI*, edited by Carlos Molpeceres, Jie Qiao, Aiko Narazaki, Proc. of SPIE 11673, Seven-digit Article CID Number (DD/MM/YYYY); (DOI URL).

ISSN: 0277-786X
ISSN: 1996-756X (electronic)

ISBN: 9781510641815
ISBN: 9781510641822 (electronic)

Published by
SPIE
P.O. Box 10, Bellingham, Washington 98227-0010 USA
Telephone +1 360 676 3290 (Pacific Time)
SPIE.org
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Contents

AI AND NEW TRENDS IN INDUSTRIAL ULTRAFAST PROCESSING

11673 03 **Prediction of ultrashort pulse laser ablation processing using machine learning (Invited Paper)** [11673-1]

11673 05 **High laser power resistance phase-only spatial light modulator for laser processing cyber-physical system** [11673-3]

11673 06 **Estimation of the mobility of low temperature polycrystalline silicon thin film transistors through deep learning** [11673-4]

OPTIMIZATION OF ENERGY DELIVERY IN ULTRAFAST PROCESSING

11673 08 **Ultrafast laser machining: process optimization and applications (Invited Paper)** [11673-6]

11673 0A **Optimized temporal energy deposition for advanced processing of Si and SiC based on highly flexible TruMicro series 2000** [11673-8]

ADVANCES IN GLASS PROCESSING

11673 0D **Laser-fabricated axicons as an alternative to conventional optics for glass dicing (Invited Paper)** [11673-11]

11673 0H **Inscription in the glass of efficient Gauss to top-hat converters based on Pancharatnam-Berry phase by high power femtosecond laser pulses** [11673-15]

WELDING AND CUTTING WITH ULTRAFAST LASERS

11673 0K **Welding with ultrashort laser pulses: recent developments at TRUMPF** [11673-18]

FUNDAMENTALS

11673 0O **Dynamics of titanium ablation suppression induced by below-ablation-threshold femtosecond laser pulse irradiation** [11673-22]

11673 0Q **Analytical model of time-dependent photoionization and nonlinear absorption of few-cycle laser pulses in dielectrics** [11673-24]

NANOSCALE MATERIAL PROCESSING IN ELECTRONICS

11673 0S **Functional surface formation by efficient laser ablation using single-pulse and burst-modes** [11673-26]

11673 0U **Mid-infrared free electron laser induced periodic surface structures on semiconductors (Best Student Paper Award)** [11673-28]

INTEGRATION OF DEVICES

11673 0W **Advancing integrated photonics and microreactor technologies with ultrafast laser processing (Invited Paper)** [11673-30]

11673 0X **Laser induced forward transfer of solder paste for microelectronics assembly applications** [11673-31]

11673 0Y **Microprocessing machinability of organic material for semiconductor packaging by 248 nm excimer laser** [11673-32]

NEW PROCESSES FOR ELECTRONICS, PHOTONICS AND PV

11673 15 **Simulation of transference regimes in BA-LIFT of water-glycerol and LIFT of high-viscosity silver pastes (Invited Paper)** [11673-39]

11673 17 **Direct laser writing of graded-index SiGe waveguides via phase segregation** [11673-41]

11673 19 **Ultra-short pulses at high average power in the Laser MicroJet** [11673-43]

POSTER SESSION

11673 1B **High-speed observation of damage generation during ultrashort pulse laser drilling of wide-bandgap materials** [11673-45]

11673 1C **Influence of ambient pressure on SS316L plate fabricated with single mode fiber laser** [11673-46]

11673 1D **Effect of preheating on pure copper welding by hybrid laser system with blue laser and IR laser (Best Student Poster Award)** [11673-47]